

4

3

2

FSCM DWG NO.

SH

REV

REVISIONS

ZONE	REV	DESCRIPTION	DATE	APPROVED
-	03	SILKSCREEN LABELING	1-30-12	ARMANDO

17. THIS PCB TO BE ROHS COMPLIANT IN MATERIALS AND MANUFACTURING PROCESSES.

16. PLEASE MAKE SURE PRECAUTIONS ARE TAKEN ON THIS BOARD WITH REGARDS TO OVER ETCHING.

15. ALL PEREGRINE BOARDS TO USE NETLIST COMPARISON TO VERIFY GERBER DATA PRIOR TO MANUFACTURING USING THE SUPPLIED IPC-D-356A NETLIST. REMOVE BOARD OUTLINE PRIOR TO NET COMPARE AND FAB. OK FOR RF CONNECTOR PADS TO REACH BOARD EDGE.

14. RF TRANSMISSION LINE TOLERANCE TO BE AS FOLLOWS:
50 OHMS +/- 5%.
22 MIL WIDTH 7 MIL GAP
CROSS-SECTION SHALL BE SUPPLIED WITH PARTS WITH THICKNESS OF T-LINES VERIFIED.
PCB VENDOR HAS AUTHORITY TO MODIFY RF TRACE WIDTH AND AIR GAP TO INSURE 50 OHM IMPEDANCE.

13. SURFACE MOUNT PAD SOLDER PLATING MUST BE FLAT TO A MAXIMUM OF .003" ABOVE BOARD

12. PLATE WITH 8 +/- 2 uIN MINIMUM IMMERSION GOLD OVER 175 +/- 75 uIN MINIMUM ELECTROLESS NICKEL OVER COPPER.

11. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

10. FABRICATE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.

9. BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-0. VENDOR'S UL LOGO OR DESIGNATION AND DATE SHALL BE LOCATED ON THE BOTTOM SIDE.

8. REMOVE ALL BURRS AND BREAK SHARP EDGES .015 MAX.

7. APPLY SILKSCREEN, AS REQUIRED, USING WHITE EPOXY INK.

6. WARP OR TWIST OF BOARD SHALL NOT EXCEED 10X.

5. APPLY SOLDERMASK LIQUID PHOTO IMAGEABLE (LPI) OVER BARE GOLD. SOLDERMASK TO BE PER IPC-SM-840, CLASS T, COLOR: GREEN. ALL EXPOSED CONDUCTIVE SURFACES TO BE GOLD PLATED. U1 SOLDERMASK DEFINED PADS ARE TO BE ALIGNED PRECISELY. NO SOLDERMASK ON U1 SMT PADS.

4. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/-10% OF ARTWORK ORIGINALS, UNLESS OTHERWISE NOTED.

3. ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION. LAYER TO LAYER REGISTRATION SHALL BE WITHIN .003". ALL HOLES SURROUNDED BY LAND SHALL HAVE A MINIMUM ANULAR RING OF .003.

2. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING. ALL PLATED THROUGH HOLES TO BE COPPER PLATED IN ACCORDANCE WITH MIL-C-14550. .0008" IN HOLES MINIMUM.

1. MATERIAL: ROGERS 4350 ON OUTER LAYERS AND FR-4 ON INNER LAYERS.
OVERALL BOARD THICKNESS TO BE .062 +/- .005

LAYOUT DETAIL
4 LAYER

10 MIL CORE

21 MIL CORE

10 MIL CORE

SILKSCREEN (TOP SIDE)

SOLDERMASK (TOP SIDE)

LAYER 1 (TOP SIDE 0.5 OZ.)

LAYER 2 (OND PLANE 0.0062 MIL)

LAYER 3 (OND PLANE 0.0062 MIL)

LAYER 4 (BOTTOM SIDE 0.5 OZ.)


SOLDERMASK (BOTTOM SIDE)

SILKSCREEN (BOTTOM SIDE)

.002 +/- .005

500mil

1475mil



LAYER 2 (PRIMARY RUNG)

8

SIZE

QTY

SYM

PLATED

THR/PRTL

TOL

0.008	9	X	YES	THR	+/-0.003
0.037	10	□	YES	THR	+/-0.003
0.01	284	X	YES	THR	+/-0.003

QTY REQD	FROM NO.	PART OR EQUIVALENT NO.	NUMERICAL VALUE OR DESCRIPTION	MATERIAL SPECIFICATION
UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN INCHES TOLERANCES ARE FRACTIONS DECIMALS ANGLES ± .005 ± .0005 ± .001				
MATERIAL				
FINISH				
NEXT ASSY USED ON				
APPLICATION				
DO NOT SCALE DRAWING				

CONTRACT NO.

APPROVALS

DATE

DRAWN

CHECKED

ISSUED


STEVE JOHNSON

KEVIN ROBERTS

6-02-11

6-02-11

COMPANY



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TITLE

PCB, PE42621 2x2 EVK

SIZE

FSCM NO.

DWG NO.

REV.

C

101-0593

03

SCALE: NONE

SHEET

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